

Abstract

**Method for cleaning a semiconductor wafer composed of silicon
directly after a process of polishing of the semiconductor
wafer**

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- Method for cleaning a semiconductor wafer composed of silicon
directly after a process of chemical mechanical polishing of
10 the wafer, comprising the steps in the order indicated:
- a) transferring the wafer from a polishing plate to a first
cleaning module, wherein both side surfaces of the
semiconductor wafer are sprayed at least once with water not
more than 1000 Pa in the course of the transfer;
 - 15 b) cleaning the wafer between rotating rollers with supply of
water;
 - c) spraying the side surfaces of the wafer with an aqueous
solution containing HF and a surfactant, at not more than 70
000 Pa;
 - 20 d) spraying the side surfaces of the wafer with water at not
more than 20 000 Pa;
 - e) dipping the wafer into an aqueous alkaline cleaning
solution;
 - f) cleaning the wafer between rotating rollers with supply of
25 water;
 - g) spraying the wafer with water;
 - h) drying the wafer.

Fig. 2